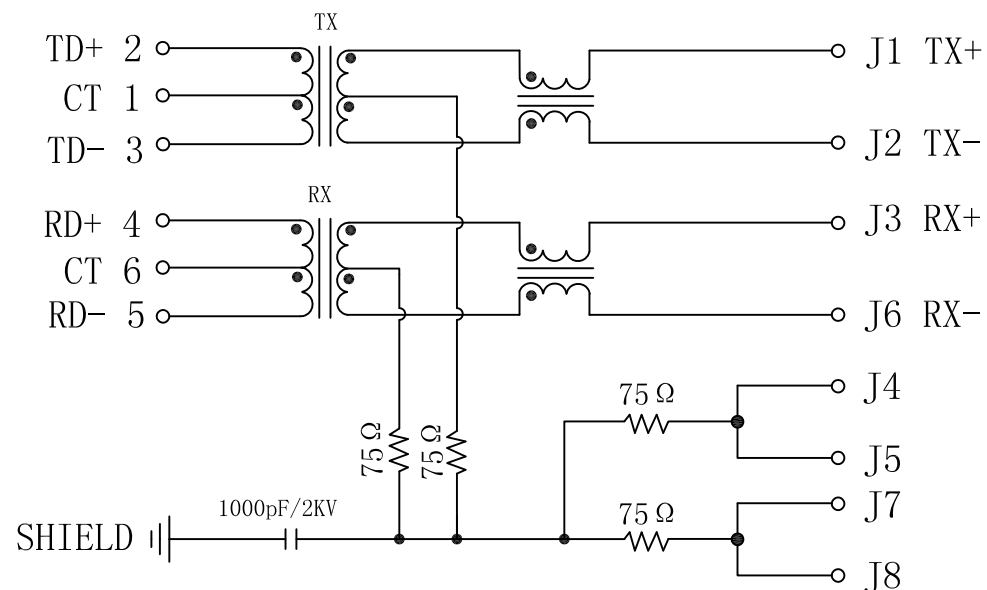


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
B	REL		2014-03-26	

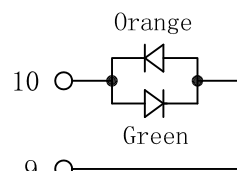
PC BOARD CONNECTIONS



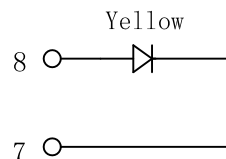
RJ45 CONNECTOR

ELECTRICAL SPECIFICATIONS @25°C

- Turn Ratio($\pm 3\%$):
TX=1CT:1CT RX=1CT:1CT
- Inductance OCL:
350uH MIN @ 100KHz 0.1V 8mA DC Bias
- DCR:
1.2 Ω MAX
- Insertion Loss:
-1.0dB MAX @ 1-100MHz
- Return Loss:
-18dB MIN @ 1-30MHz
-15dB MIN @ 30-60MHz
-12dB MIN @ 60-100MHz
- Cross talk:
-40dB MIN @ 1-30MHz
-35dB MIN @ 30-60MHz
-30dB MIN @ 60-100MHz
- Common Mode Rejection:
-30dB MIN @ 1-100MHz
- Hipot Test:1500Vrms
- Operating Temperature Range: 0°C TO 70°C



Left LED



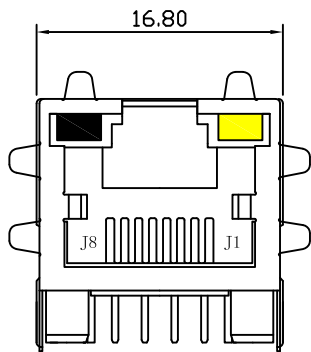
Right LED

Emitting Color	λ p(nm)	VF@IF=20mA	IR @VR=5V
Green	565	1.8~2.6V	10 μ A max
Yellow	585	1.8~2.6V	10 μ A max
Orange	610	1.8~2.6V	10 μ A max

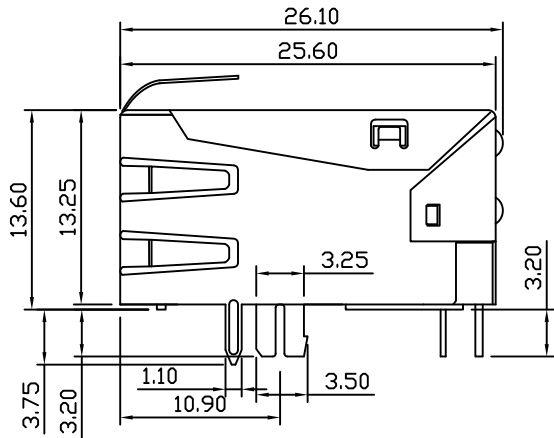
X:X	± 0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	± 0.20	CHKD:		
X:XXX	± 0.05	DR: TOM	TITLE: RJ45 Connector with 10/100 Base-T Integrated Magnetics	
ANGLES	$\pm 1^\circ$	UNIT: mm	PART NO.: LPJ2011KONL	
		SCALE: 2/1	SHEET: 1/2	REV: B
		DWG NO.: LP14032621		

Mechanical:

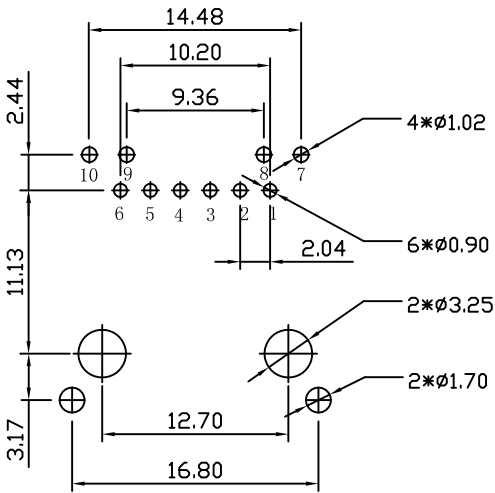
REV.	ECN NO.	DESCRIPTION	DATE	APPD
B	REL		2014-03-26	



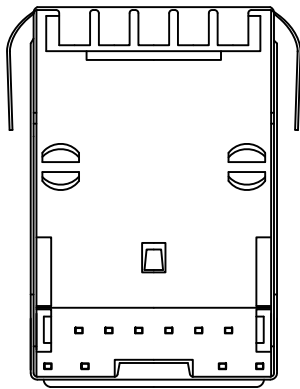
Front Side View



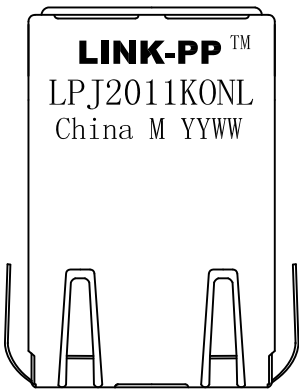
Left Side View



Suggested PCB Layout(Top View)



Bottom Side View



Top Side View

NOTES:

- 1.Meets IEEE 802.3 specification
- 2.Connector Materials:
Housing Material:Thermoplastic PBT+30%G.F UL94V-0
Contact Material:Phosphor Bonze C5210R-EH Thickness=0.35mm
Pins:Brass C2680R-H Thickness=0.35mm
Shield:SUS 201-1/2H Thickness=0.2mm
Contact plating: Gold 6 micro-inches min.In contact area.
- 3.Wave solder tip temperature: 265℃ Max, 5 Sec Max



X:X	±0.25	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.20	CHKD:		
X:XXX	±0.05	DR: TOM	TITLE: RJ45 Connector with 10/100 Base-T Integrated Magnetics	
ANGLES	±1°	UNIT: mm	PART NO. : LPJ2011KONL	
	SCALE: 2/1	SHEET: 2/2	REV: B	DWG NO. : LP14032621